

## PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Silverbrook Research Pty Ltd	08/18/2012
RECEIVING PARTY DATA	
Name:	Precision Mechatronics Pty Ltd
Street Address:	44-48 Waterloo Road
City:	North Ryde
State/Country:	AUSTRALIA
Postal Code:	2113
PROPERTY NUMBERS Total: 1	
Property Type	Number
Patent Number:	6557978
CORRESPONDENCE DATA	
Fax Number:	
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ATTORNEY DOCKET NUMBER:	WSM07US
NAME OF SUBMITTER:	Leonie News
Signature:	/leonie news/
Date:	06/05/2013
Total Attachments: 7 source=ASN WSM Assignment SR-PM 18 August 2012 5-17-13#page1.tif source=ASN WSM Assignment SR-PM 18 August 2012 5-17-13#page2.tif	

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source=ASN WSM Assignment SR-PM 18 August 2012 5-17-13#page7.tif

ASSIGNMENT OF PATENT RIGHTS

THIS ASSIGNMENT OF PATENT RIGHTS (the "Assignment") is executed, acknowledged and delivered by Silverbrook Research Pty Ltd, an Australian proprietary company, with its principal place of business at 393 Darling St Balmain NSW 2041, Australia ("Assignor"), and by Precision Mechatronics Pty Ltd, an Australian proprietary company, with its principal place of business at 44-48 Waterloo Road North Ryde NSW 2113, Australia ("Assignee").

"Listed Patents" means the provisional patent applications, patent applications, and patents listed in Exhibit A.

"Patents" means, all (a) Listed Patents; (b) national (of any country of origin) and multinational patents, patent applications and counterparts filed in respect of the Listed Patents, including, without limitation, certificates of invention and utility models; and (c) any items in the foregoing category (b) whether or not expressly listed as Listed Patents and whether or not claims in any of the foregoing have been rejected, withdrawn, cancelled, or the like.

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN:

For good and valuable consideration, the receipt of which is hereby acknowledged, Assignor agrees to and does hereby irrevocably sell, assign, transfer and convey unto said Assignee, and Assignee hereby accepts, all of Assignor's right, title, and interest (i) in and to the Patents, the same to be held and enjoyed by said Assignee for its own use, and for the use of its successors, assigns, or other legal representatives to the end of the term or terms for which said Patents may be granted as fully and entirely as the same would have been held and enjoyed by Assignor if this Assignment had not been made; (ii) in and to causes of action and enforcement rights for the Patents including all rights to pursue damages, injunctive relief and other remedies for past and future infringement of the Patents; and (iii) to apply in any and all countries for the world for patents; certificates of invention or other governmental grants for the Patents. Assignor also hereby authorizes the respective patent office or governmental agency in each jurisdiction to issue any and all patents or certificates of invention which may be granted upon any of the Patents in the name of Assignee, as the assignee to the entire interest therein.

This Assignment shall be binding upon and shall inure to the benefit of the parties and their respective successors and assigns.

This Assignment shall be governed by, and construed in accordance with, the laws of the United States in respect to patent issues and in all other respects by the laws of New South Wales, Australia, without giving effect to the conflict of laws rules thereof.

IN WITNESS WHEREOF, Assignor has caused this Assignment to be executed as of this day of 18 August 2012.

Patent Assignment

Silverbrook Research - Precision Mechatronics

ASSIGNOR:

WITNESS:

Silverbrook Research Pty Ltd

By:         *UJZ*        

By:         *M. P. Lee*        

Name:         *KIA SILVER BROOK*        

Name:         *MARGARET FAY LEE*        

Title:         *CEO*        

Date:         *18 AUGUST 2012*        

Date:         *18 AUGUST 2012*

## EXHIBIT A

## LISTED PATENTS

case ref.	official no.	application no.	CC	Title
WSM01NPUS	6716666	10/129502	US	Wafer Scale Molding of Protective Caps
WSM01US	10/043299	10/043299	US	Wafer Scale Molding of Protective Caps
WSM02NPUS	10/129501	10/129501	US	Molding of Protective Caps
WSM02US	10/043350	10/043350	US	Packaged Accelerometer
WSM03NPUS	6949217	10/129500	US	Use of Infrared Radiation In Molding of Protective Caps
WSM03US	10/043300	10/043300	US	Use of Infrared Radiation In Molding of Protective Caps
WSM04NPUS	6750083	10/129499	US	Method of Masking Microelectronic Semiconductor Chips With Protective Caps
WSM04US	10/043351	10/043351	US	Use of Protective Caps As Mask at A Wafer Scale
WSM05NPUS	7014451	10/129504	US	Molding Assembly for Wafer Scale Molding of Protective Caps
WSM06NPUS	6777259	10/129505	US	Accelerometer Protected by Caps Applied at the Wafer Scale
WSM06US	10/043295	10/043295	US	Accelerometer Protected by Caps Applied at the Wafer Scale
WSM07NPUS	6923524	10/250967	US	Inkjet Device Encapsulated at the Wafer Scale
WSM07US	6557978	10/040455	US	Inkjet Device Encapsulated at the Wafer Scale
WSM08NPUS	6991207	10/466072	US	Molds for Wafer Scale Molding of Protective Caps
WSM08US	6766998	10/040456	US	Molds for Wafer Scale Molding of Protective Caps
WSM09NPUS	6967354	10/466059	US	Light Emitting Semiconductor Package
WSM09US	6759723	10/040473	US	Light Emitting Semiconductor Package
WSM10NPUS	6870259	10/466060	US	Wafer Scale Fiber Optic Termination
WSM10US	10/040405	10/040405	US	Wafer Scale Fiber Optic Termination
WSM11US	7875230	10/853270	US	Method of Manipulating A Sheet of Thermoplastic Material
WSM20US	6925875	10/893376	US	Packaged Accelerometer
WSM21US	7618575	10/898214	US	Method for Wafer Scale Molding of Protective Caps
WSM29US	7095109	10/986362	US	Optical Fiber Terminator Package
XMB076US	7407614	11/064005	US	Method for Forming at Least One Protective Cap
XMB077US	7284976	11/064006	US	Moulding Assembly for Forming at Least One Protective Cap
ZF004US	6878564	10/853175	US	Method of Manufacturing A Light Emitting Semiconductor Package
ZF211US	7160743	11/065147	US	Using Protective Caps to Fabricate Light Emitting Semiconductor Packages
ZG112US	6989292	10/728929	US	Chips With Wafer Scale Caps Formed by Molding
ZG113US	7126216	10/728808	US	Two Part Mold for Wafer Scale Caps
ZG114US	6977189	10/728800	US	Wafer Scale Caps Located by Molding
ZG115US	6982189	10/728930	US	Molded Wafer Scale Cap Array
ZG116US	7173332	10/728985	US	Placement Tool for Wafer Scale Caps
ZG117US	7026176	10/728923	US	Mold Making Method for Wafer Scale Caps
ZG118US	6979599	10/728798	US	Chip With Molded Cap Array
ZG119US	6812062	10/728799	US	Molded Wafer Scale Cap

ZG123US	7001793	10/791840	US	Method of Protecting Microfabricated Devices With Protective Caps
ZG198US	7008819	10/949350	US	Method of Fabricating an Array of Wafer Scale Polymeric Caps
WSM01-AU	2002216845	2002216845	AU	Wafer Scale Molding of Protective Caps
WSM01PAU	PR2448	PR2448	AU	A Method and Apparatus (WSM01)
WSM02-AU	2002216846	2002216846	AU	Molding of Protective Caps
WSM02PAU	PR2449	PR2449	AU	A Method (WSM02)
WSM03-AU	2002218865	2002218865	AU	Use of Infrared Radiation In Molding of Protective Caps
WSM03PAU	PR2450	PR2450	AU	A Method (WSM03)
WSM04-AU	2002218866	2002218866	AU	Use of Protective Caps As Masks at A Wafer Scale
WSM04PAU	PR2451	PR2451	AU	A Method (WSM04)
WSM05-AU	2002218867	2002218867	AU	Molding Assembly for Wafer Scale Molding of Protective Caps
WSM05PAU	PR2452	PR2452	AU	An Apparatus and Method (WSM05)
WSM06-AU	2002218868	2002218868	AU	Accelerometer Protected by Caps Applied at the Wafer Scale
WSM06PAU	PR2453	PR2453	AU	An Apparatus (WSM06)
WSM07-AU	2002218869	2002218869	AU	Inkjet Device Encapsulated at the Wafer Scale
WSM07PAU	PR2454	PR2454	AU	An Apparatus (WSM07)
WSM08-AU	2002218870	2002218870	AU	Molds for Wafer Scale Molding of Protective Caps
WSM08PAU	PR2455	PR2455	AU	An Apparatus (WSM08)
WSM09-AU	2002218871	2002218871	AU	Light Emitting Semiconductor Package
WSM09PAU	PR2456	PR2456	AU	An Apparatus (WSM09)
WSM10-AU	2002218872	2002218872	AU	Wafer Scale Fiber Optic Termination
WSM10PAU	PR2457	PR2457	AU	An Apparatus (WSM10)
WSM12-AU	2004202254	2004202254	AU	Wafer Scale Molding of Protective Caps
WSM13-AU	2004202256	2004202256	AU	Encapsulated Ink Jet Device
WSM14-AU	2004202251	2004202251	AU	Wafer Scale Molding of Protective Caps
WSM15-AU	2004202257	2004202257	AU	Encapsulated Light Emitting Semiconductor Packages
WSM16-AU	2004202260	2004202260	AU	Encapsulated Fiber Optic Terminations
WSM17-AU	2004202411	2004202411	AU	An Apparatus for Fabricating Packaged Semiconductor Devices
WSM18-AU	2004202412	2004202412	AU	A Method of Separating A Plurality of Micro-Fabricated Devices On A Common Substrate
WSM22-AU	2004214603	2004214603	AU	A Moulding Apparatus for Moulding Protective Caps for Micro-Fabricated Structures
WSM23-AU	2004214604	2004214604	AU	Encapsulated Ink Jet Printhead Assembly
WSM24-AU	2004214605	2004214605	AU	Encapsulated Optical Integrated Circuit Assembly
WSM25-AU	2004214606	2004214606	AU	Encapsulated Light-Emitting Integrated Circuit Assembly
WSM26-AU	2004214607	2004214607	AU	An Integrated Circuit Assembly Incorporating Protective Caps
WSM27-AU	2004220750	2004220750	AU	A Method of Preparing A Semiconductor Chip Having A Protected Microfabricated Device
WSM28-AU	2004220751	2004220751	AU	A Method of Applying Caps to Microfabricated Devices
WSM30-AU	2004233537	2004233537	AU	A Method of Molding A Thermoplastic Sheet
WSM31-AU	2005201836	2005201836	AU	Accelerometer Protected by Caps Applied at the Wafer Scale

WSM01-DE	1356510	2729352.1	DE	Wafer Scale Modling of Protective Caps
WSM02-DE	1356513	2729353.9	DE	Molding of Protective Caps
WSM03-DE	1356514	2729354.7	DE	Use of Infrared Radiation In Molding of Protective Caps
WSM04-DE	1356511	2729355.4	DE	Use of Protective Caps at A Wafer Scale
WSM05-DE	1356515	2729356.2	DE	Modling Assembly for Wafer Scale Molding of Protective Caps
WSM08-DE	1360719	2729359.6	DE	Molds for Wafer Scale Molding of Protective Caps
WSM01-EP	1356510	2729352.1	EP	Wafer Scale Modling of Protective Caps
WSM02-EP	1356513	2729353.9	EP	Molding of Protective Caps
WSM03-EP	1356514	2729354.7	EP	Use of Infrared Radiation In Molding of Protective Caps
WSM04-EP	1356511	2729355.4	EP	Use of Protective Caps at A Wafer Scale
WSM05-EP	1356515	2729356.2	EP	Modling Assembly for Wafer Scale Molding of Protective Caps
WSM06-EP	1358489	2729357	EP	Production Process for Accelerometer Protected by Caps Applied at the Wafer Scale
WSM07-EP	2729358.8	2729358.8	EP	Inkjet Device Encapsulated at the Wafer Scale
WSM08-EP	1360719	2729359.6	EP	Molds for Wafer Scale Molding of Protective Caps
WSM09-EP	2729360.4	2729360.4	EP	Light Emitting Semiconductor Package
WSM10-EP	2729361.2	2729361.2	EP	Wafer Scale Fibre Optic Termination
WSM01-FR	1356510	2729352.1	FR	Wafer Scale Modling of Protective Caps
WSM02-FR	1356513	2729353.9	FR	Molding of Protective Caps
WSM03-FR	1356514	2729354.7	FR	Use of Infrared Radiation In Molding of Protective Caps
WSM04-FR	1356511	2729355.4	FR	Use of Protective Caps at A Wafer Scale
WSM05-FR	1356515	2729356.2	FR	Modling Assembly for Wafer Scale Molding of Protective Caps
WSM08-FR	1360719	2729359.6	FR	Molds for Wafer Scale Molding of Protective Caps
WSM01-GB	1356510	2729352.1	GB	Wafer Scale Modling of Protective Caps
WSM02-GB	1356513	2729353.9	GB	Molding of Protective Caps
WSM03-GB	1356514	2729354.7	GB	Use of Infrared Radiation In Molding of Protective Caps
WSM04-GB	1356511	2729355.4	GB	Use of Protective Caps at A Wafer Scale
WSM05-GB	1356515	2729356.2	GB	Modling Assembly for Wafer Scale Molding of Protective Caps
WSM06-GB	1358489	2729357	GB	Production Process for Accelerometer Protected by Caps Applied at the Wafer Scale
WSM08-GB	1360719	2729359.6	GB	Molds for Wafer Scale Molding of Protective Caps
WSM01-IE	1356510	2729352.1	IE	Wafer Scale Modling of Protective Caps
WSM02-IE	1356513	2729353.9	IE	Molding of Protective Caps
WSM03-IE	1356514	2729354.7	IE	Use of Infrared Radiation In Molding of Protective Caps
WSM04-IE	1356511	2729355.4	IE	Use of Protective Caps at A Wafer Scale
WSM05-IE	1356515	2729356.2	IE	Modling Assembly for Wafer Scale Molding of Protective Caps
WSM08-IE	1360719	2729359.6	IE	Molds for Wafer Scale Molding of Protective Caps
WSM01-JP	3962688	2002-556935	JP	Wafer Scale Molding of Protective Caps
WSM02-JP	4197947	2002-556943	JP	Molding of Protective Caps
WSM03-JP	3986966	2002-556940	JP	Use of Infrared Radiation In Molding of Protective Caps
WSM04-JP	3962687	2002-556934	JP	Use of Protective Caps As Masks at A Wafer Scale

Patent Assignment

Silverbrook Research - Precision Mechatronics

WSM05-JP	4018541	2002-556941	JP	Molding Assembly and Method of Manipulating Sheet of Thermoplastic Material Using the Molding Assembly
WSM06-JP	2002-556235	2002-556235	JP	Accelerometer Protected by Caps Applied at the Wafer Scale
WSM07-JP	3963837	2002-556928	JP	Inkjet Device Encapsulated at the Wafer Scale
WSM08-JP	4259866	2002-556942	JP	An Apparatus for Molding A Sheet of Thermoplastic Material Into an Array of Microstructures
WSM09-JP	2002-556929	2002-556929	JP	Light Emitting Semiconductor Package
WSM10-JP	4004957	2002-556930	JP	Wafer Scale Fiber Optic Termination
WSM01-PCT	PCT/AU02/00008	PCT/AU02/00008	PCT	Wafer Scale Molding of Protective Caps
WSM02-PCT	PCT/AU02/00009	PCT/AU02/00009	PCT	Molding of Protective Caps
WSM03-PCT	PCT/AU02/00010	PCT/AU02/00010	PCT	Use of Infrared Radiation In Molding of Protective Caps
WSM04-PCT	PCT/AU02/00011	PCT/AU02/00011	PCT	Use of Protective Caps As Masks at A Wafer Scale
WSM05-PCT	PCT/AU02/00012	PCT/AU02/00012	PCT	Molding Assembly for Wafer Scale Molding of Protective Caps
WSM06-PCT	PCT/AU02/00013	PCT/AU02/00013	PCT	Accelerometer Protected by Caps Applied at the Wafer Scale
WSM07-PCT	PCT/AU02/00014	PCT/AU02/00014	PCT	Inkjet Device Encapsulated at the Wafer Scale
WSM08-PCT	PCT/AU02/00015	PCT/AU02/00015	PCT	Molds for Wafer Scale Molding of Protective Caps
WSM09-PCT	PCT/AU02/00016	PCT/AU02/00016	PCT	Light Emitting Semiconductor Package
WSM10-PCT	PCT/AU02/00017	PCT/AU02/00017	PCT	Wafer Scale Fiber Optic Termination
WSM01-SG	98584	200303914-6	SG	Wafer Scale Molding of Protective Caps
WSM02-SG	98582	200303912-0	SG	Modling of Protective Caps
WSM03-SG	97696	200303946-8	SG	Use of Infrared Radiation In Molding of Protective Caps
WSM04-SG	98583	200303913-8	SG	Use of Protective Caps As Masks at A Wafer Scale
WSM05-SG	98085	200304118-3	SG	Modling Assembly for Wafer Scale Molding of Protective Caps
WSM06-SG	98107	200304178-7	SG	Accelerometer Protected by Caps Applied at the Wafer Scale
WSM07-SG	98224	200304142-3	SG	Inkjet Device Encapsulated at the Wafer Scale
WSM08-SG	98233	200304155-5	SG	Molds for Wafer Scale Molding of Protective Caps
WSM09-SG	98655	200304175-3	SG	Light Emitting Semiconductor Package
WSM10-SG	98105	200304176-1	SG	Wafer Scale Fibre Optic Termination
WSM01NPUS	6716666	10/129502	US	Wafer Scale Molding of Protective Caps
WSM01US	10/043299	10/043299	US	Wafer Scale Molding of Protective Caps
WSM02NPUS	10/129501	10/129501	US	Molding of Protective Caps
WSM02US	10/043350	10/043350	US	Packaged Accelerometer
WSM03NPUS	6949217	10/129500	US	Use of Infrared Radiation In Molding of Protective Caps



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Silverbrook Research - Precision Mechatronics

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ZG114US	6977189	10/728800	US	Wafer Scale Caps Located by Molding
ZG115US	6982189	10/728930	US	Molded Wafer Scale Cap Array
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ZG117US	7026176	10/728923	US	Mold Making Method for Wafer Scale Caps
ZG118US	6979599	10/728798	US	Chip With Molded Cap Array
ZG119US	6812062	10/728799	US	Molded Wafer Scale Cap
ZG123US	7001793	10/791840	US	Method of Protecting Microfabricated Devices With Protective Caps
ZG198US	7008819	10/949350	US	Method of Fabricating an Array of Wafer Scale Polymeric Caps